



SOD123 Diodes

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Frame 25.8669%	Nickel	7440-02-0	0.9740	40.98	105,938.7
	Manganese	7439-96-5	0.0190	0.80	2,069.0
	Cobalt	7440-48-4	0.0119	0.50	1,294.3
	Silicon	7440-21-3	0.0071	0.30	775.5
	Phosphorus	7723-14-0	0.0006	0.03	65.3
	Sulfur	7704-34-9	0.0006	0.03	65.3
	Carbon	7440-44-0	0.0012	0.05	130.5
	Iron	7439-89-6	1.3619	57.30	148,129.2
	Silver	7440-22-4	0.0002	0.01	26.1
	Total		2.3766		
Chip 0.4400%	Silicon	7440-21-3	0.040436	100.00	4,398.1
	Total		0.0404		
Bonding Wire 0.0629%	Copper	7440-50-8	0.0057	98.11	617.0
	Palladium	7440-5-3	0.0001	1.73	10.9
	Gold	7440-57-5	0.0000	0.16	1.0
	Total		0.0058		
Molding 72.1425%	Silica	60676-86-0	5.0387	76.00	548,042.2
	Epoxy resin	Trade Secret	0.6630	10.00	72,112.2
	Phenolic resin	29690-82-2	0.4972	7.50	54,078.7
	Brominated Resin	40039-93-8	0.1989	3.00	21,633.7
	Antimony trioxide	1309-64-4	0.1989	3.00	21,633.7
	Carbon Black	1333-86-4	0.0331	0.50	3,600.2
	Total		6.6298		
Plating 1.4877%	Tin	7440-31-5	0.1367	100.00	14,868.4
	Total		0.1367		
	Total mass (mg)		9.19		

